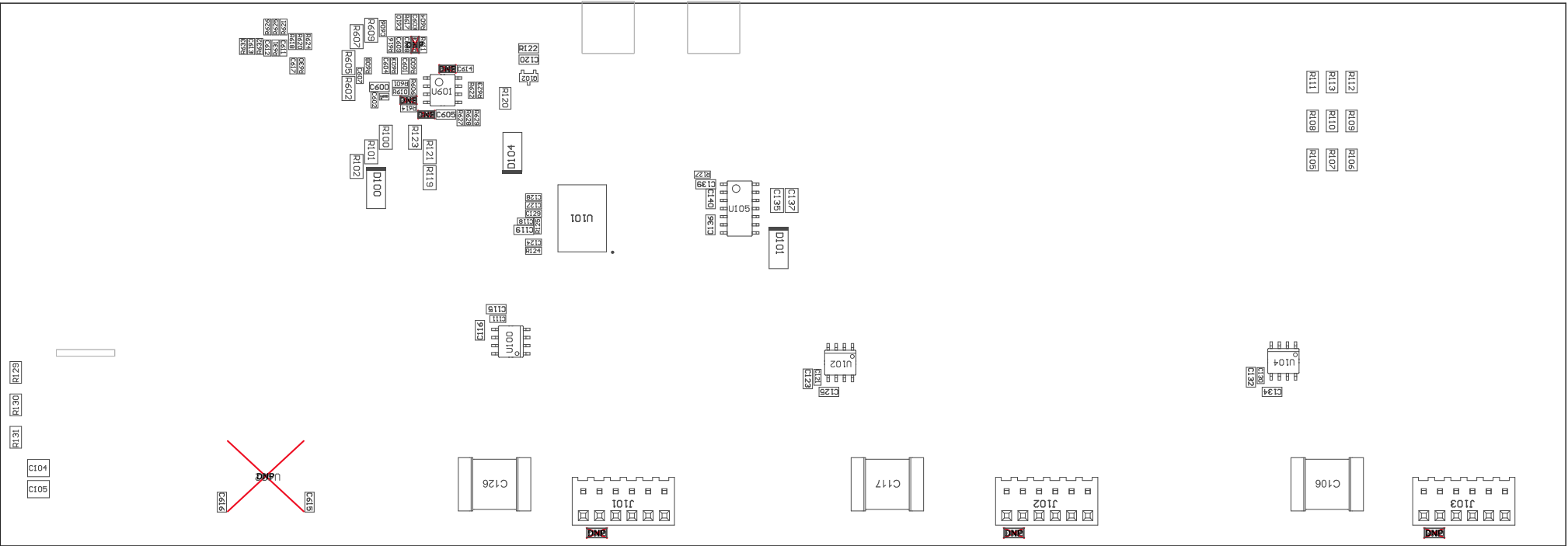


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PMP20294	REV: B	SUN REV: Not In VersionControl
	TID #: TIDM-1007		
PLOT NAME = Top Assembly Drawing	GENERATED : 10/16/2017 1:41:00 PM	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP20294	REV: B	SUN REV: Not In VersionControl
	TID #:	TIDM-1007	
PLOT NAME = Bottom Assembly Drawing	GENERATED	: 10/16/2017 1:41:01 PM	TEXAS INSTRUMENTS

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